Product type	12 mm wide tapes					
	TPL1100	**TPL1120**	**TLP2100**	**TPL2120**	**TPL4121**	**TPL5121**
desription	HTS wire with surround silver metallization.	thin HTS wire with surround silver metallization	HTS wire with laminated Cu stabilization	thin HTS wire with laminated Cu stabilization	thin HTS wire with surround copper stabilization	thin HTS wire with surround copper stabilization and SnPb solder coating
typical applications	stacks or stacked conductors for levitation and cables	high current density stacks or stacked conductors for levitation and cables	medium magnetic field coils for rotating machines etc.	medium magnetic field coils for rotating machines etc.	coils or stacks with very high current density, small bending radii designs	solder cast coils and stacked conductors
substrate	100 µm Hastelloy C276	50 µm Hastelloy C276	100 µm Hastelloy C276	50 µm Hastelloy C276	50 µm Hastelloy C276	50 µm Hastelloy C276
buffer layer	MgO	MgO	MgO	MgO	MgO	MgO
superconducting layer	GdBaCuO	GdBaCuO	GdBaCuO	GdBaCuO	GdBaCuO	GdBaCuO
metallization	Ag	Ag	Ag	Ag	Ag	Ag
stabilization	none	none	100 µm Cu soldered on HTS side	100 µm Cu soldered on HTS side	10 µm Cu surround	10 µm Cu surround coated with a thin layer of SnPb40
thickness	0.11 mm	0.06 mm	0.22 mm	0.17 mm	0.08 mm	0.08 mm
width	12 mm	12 mm	12 mm	12 mm	12 mm	12 mm
min. double bending diameter (RT, 95%)	60 mm	40 mm	60 mm	40 mm	40 mm	40 mm
recommended max. handling force	100 N (10 kg)	50 N (5 kg)	100 N (10 kg)	50 N (5 kg)	50 N (5 kg)	50 N (5 kg)
maximum rated stress (RT)	600 MPa	600 MPa	300 MPa	300 MPa	500 MPa	500 MPa
maximum rated tensile strain (95%)	0.30%	0.30%	0.30%	0.30%	0.30%	0.30%
I_c (77K, SF)	275 A to 500 A	275 A to 500 A	275 A to 500 A	275 A to 500 A	275 A to 500 A	275 A to 500 A